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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

10/29/02

Applicant

Paul A. Farrar

Appl. No.

09/909,181

Filed

July 19, 2001

For

A METHOD OF USING

FOAMED INSULATORS IN

THREE DIMENSIONAL

MULTICHIP STRUCTURES

Examiner

Chris C. Chu

Group Art Unit 2815

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: United States Patent and Trademark Office, P.O. Box 2327, Arlington, VA 22202, on

n, v A 22202, on

October 7, 2002

Linda H. Liu, Reg. No. 51,240

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SUBMISSION OF PROPOSED DRAWING AMENDMENT FOR APPROVAL BY EXAMINER

United States Patent and Trademark Office P.O. Box 2327 Arlington, VA 22202

Dear Sir:

Enclosed please find one (1) sheet of drawing designating the proposed amendment to Figure 5 of the drawings in this application for which approval by the Examiner is requested. The amended drawing is intended to overcome certain objections asserted by the Examiner in the Office Action mailed July 5, 2002 and conform to suggestions made by the Examiner in that same Office Action.

Specifically, the amended drawing shows a fourth insulating layer formed on the lower surface of the first chip. No new matter is added as the fourth insulating layer shown in the amended drawing is clearly described in Page 3 Line 30 to Page 4 Line 1 of the specification, Page 8 Line 26-28 of the specification, and Claim 17 of the claims as originally filed.

TECHNOLOGY CENTER 2800

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July 19, 2001

Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: 10/7/2002

By:

Linda H. Liu

Registration No. 51,240

Attorney of Record

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